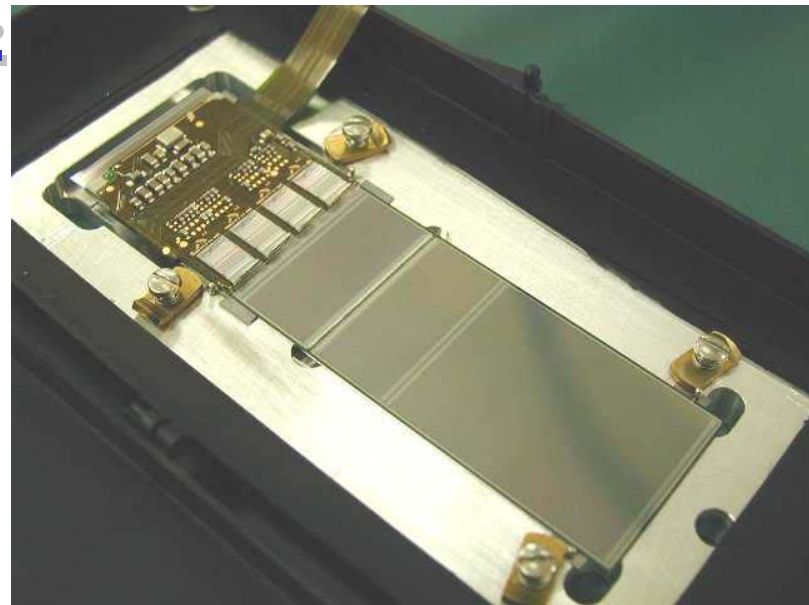
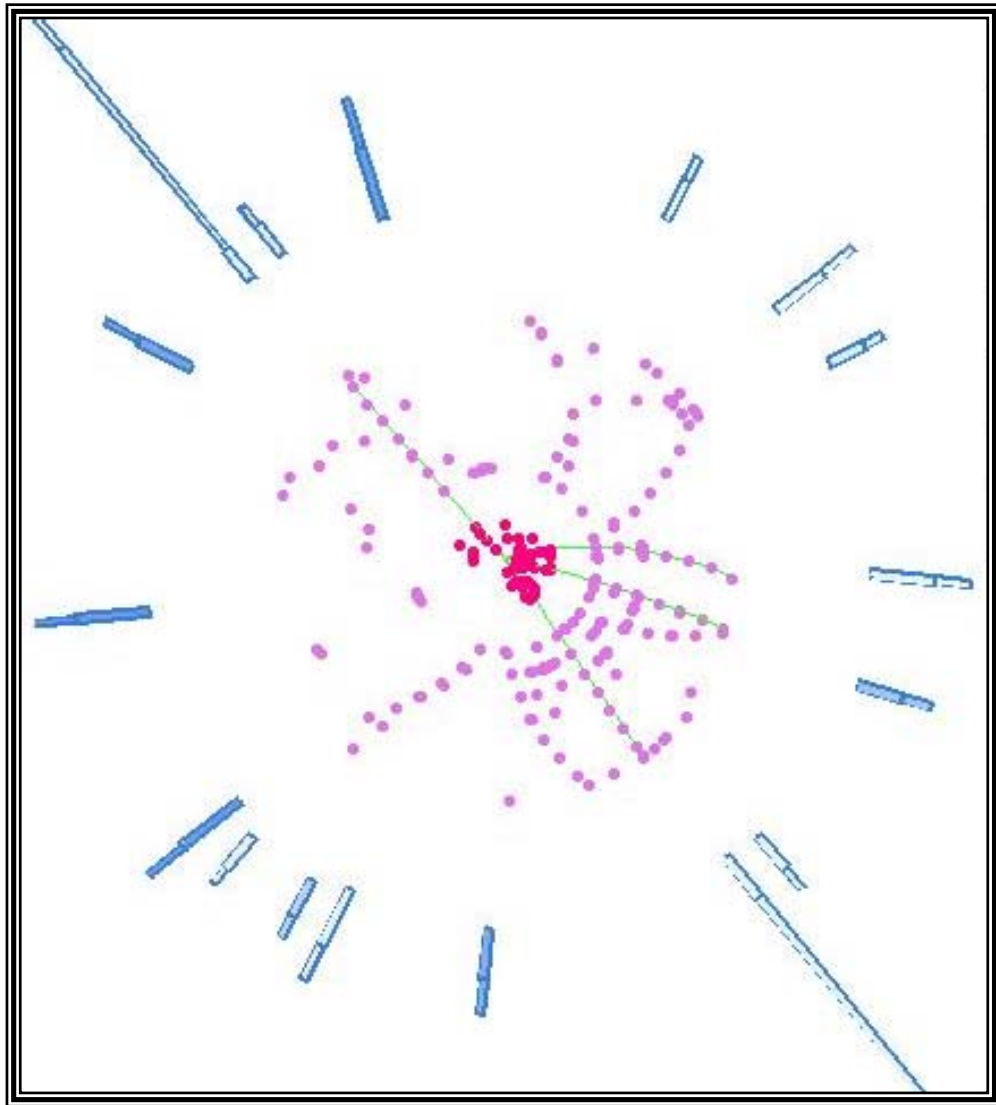
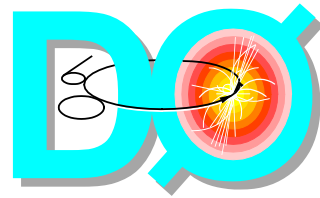
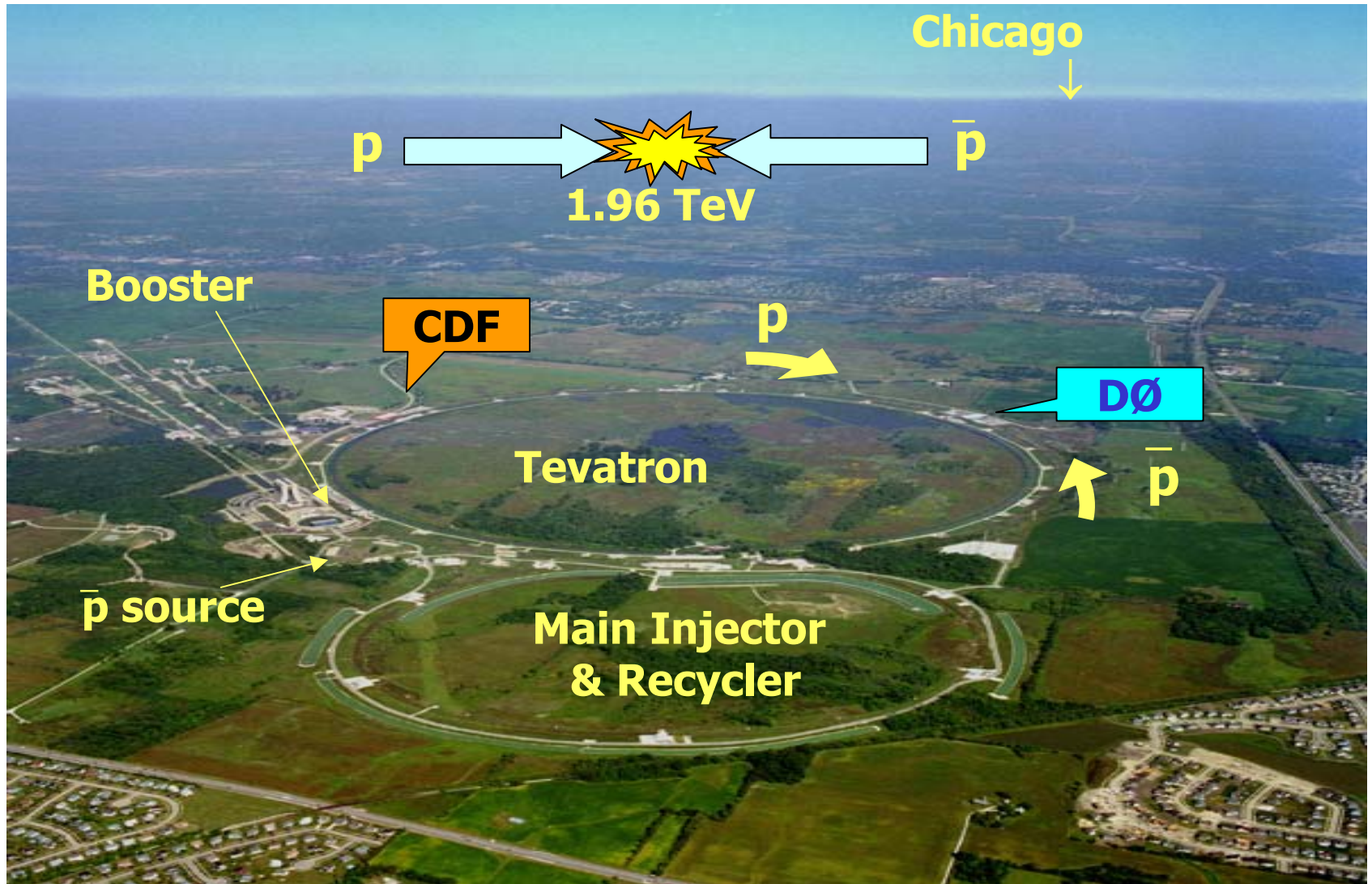


The DØ Tracking System for Run II



George Ginther
University of Rochester
for the DØ Collaboration

The Fermilab Tevatron Collider



An Opportunity

● Explore the energy frontier

● searches

- Higgs boson
- supersymmetry
- extra dimensions
- quark or lepton compositeness
- new dynamics

● precision measurements of W, Z and top

● B physics

● QCD studies

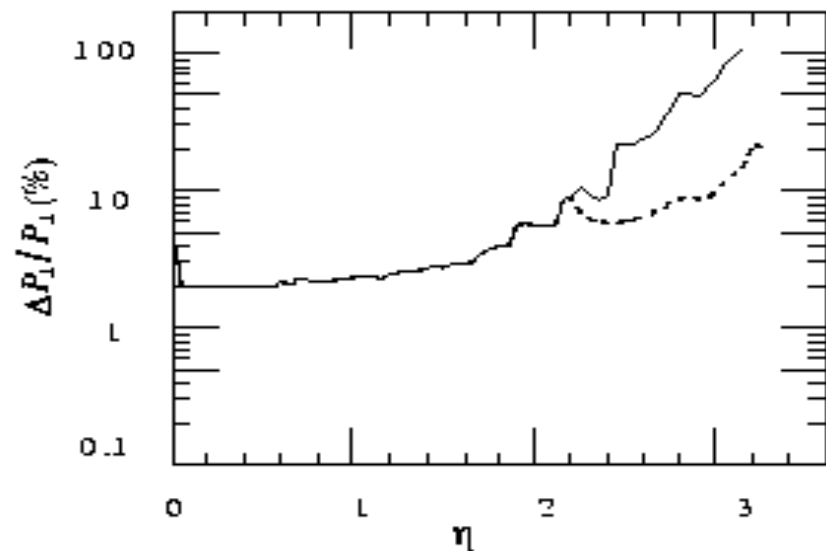
● To take best advantage of this opportunity

- large integrated luminosities (Run IIA $\Rightarrow \sim 2 \text{ fb}^{-1}$)
- electron, muon, tau, jet (including b jets) and missing E_t measurement capabilities

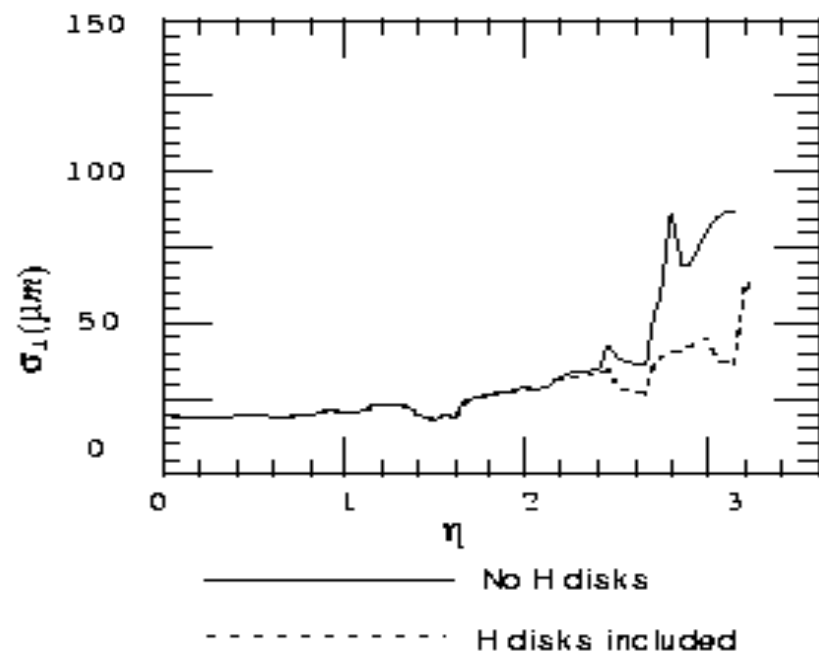
DØ Tracker Design

- Tracking system for Run II
 - 2 Tesla superconducting solenoidal magnet
 - Silicon Microstrip Tracker (SMT) and Central Fiber Tracker (CFT)
- Good 3D track reconstruction performance for high- p_T (top, Higgs, EW, NP) and low- p_T (B) tracks out to $|\eta| < 3$
- Momentum resolution $\approx 2\%$ at $p_T = 1 \text{ GeV}/c$ for $|\eta| < 1$
- Impact parameter resolution within $30 \mu\text{m}$
 - SMT H disks are employed to achieve these resolutions at high $|\eta|$

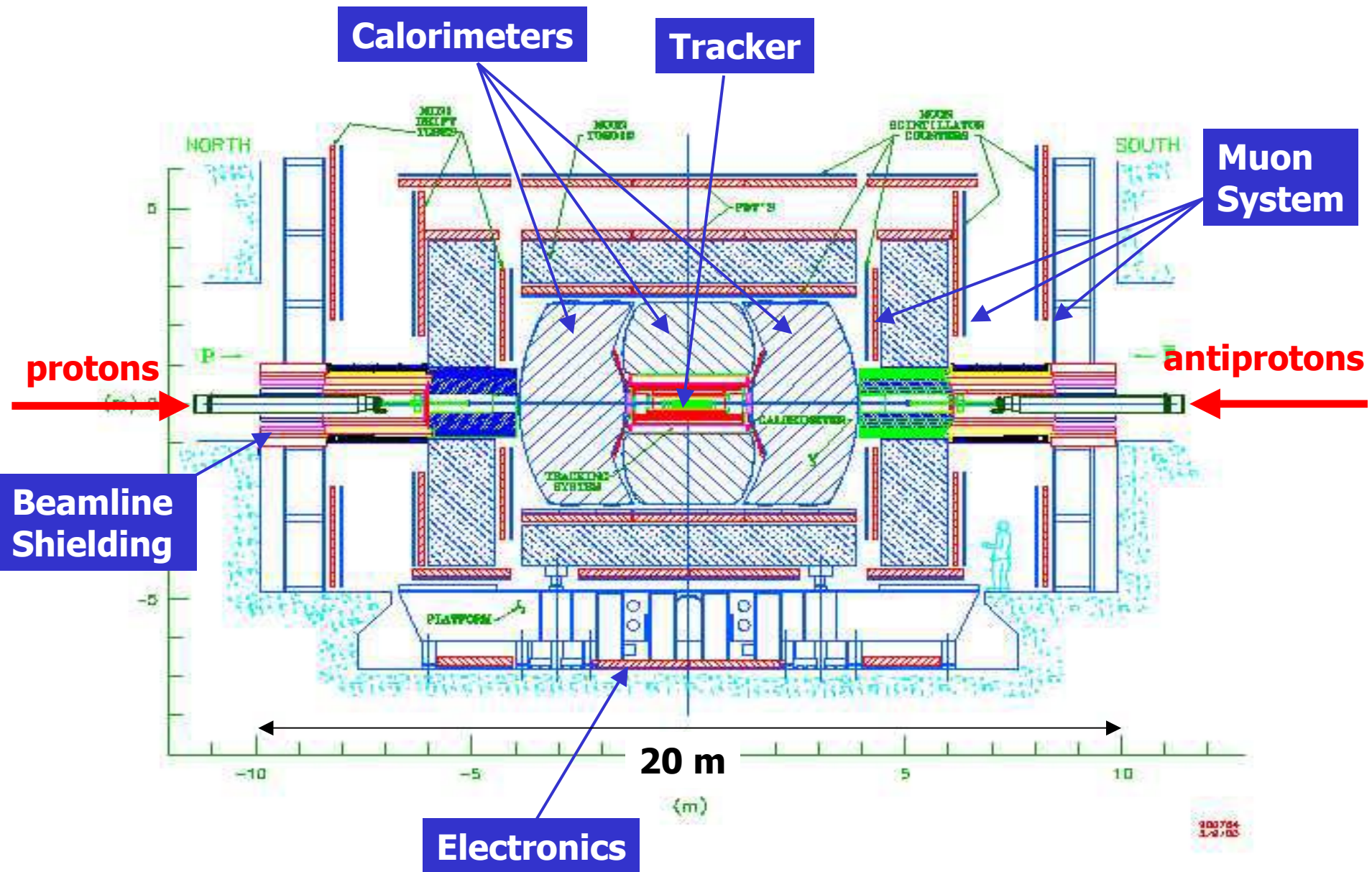
Tracking System Pt Resolution (1 GeV/c Pt track)



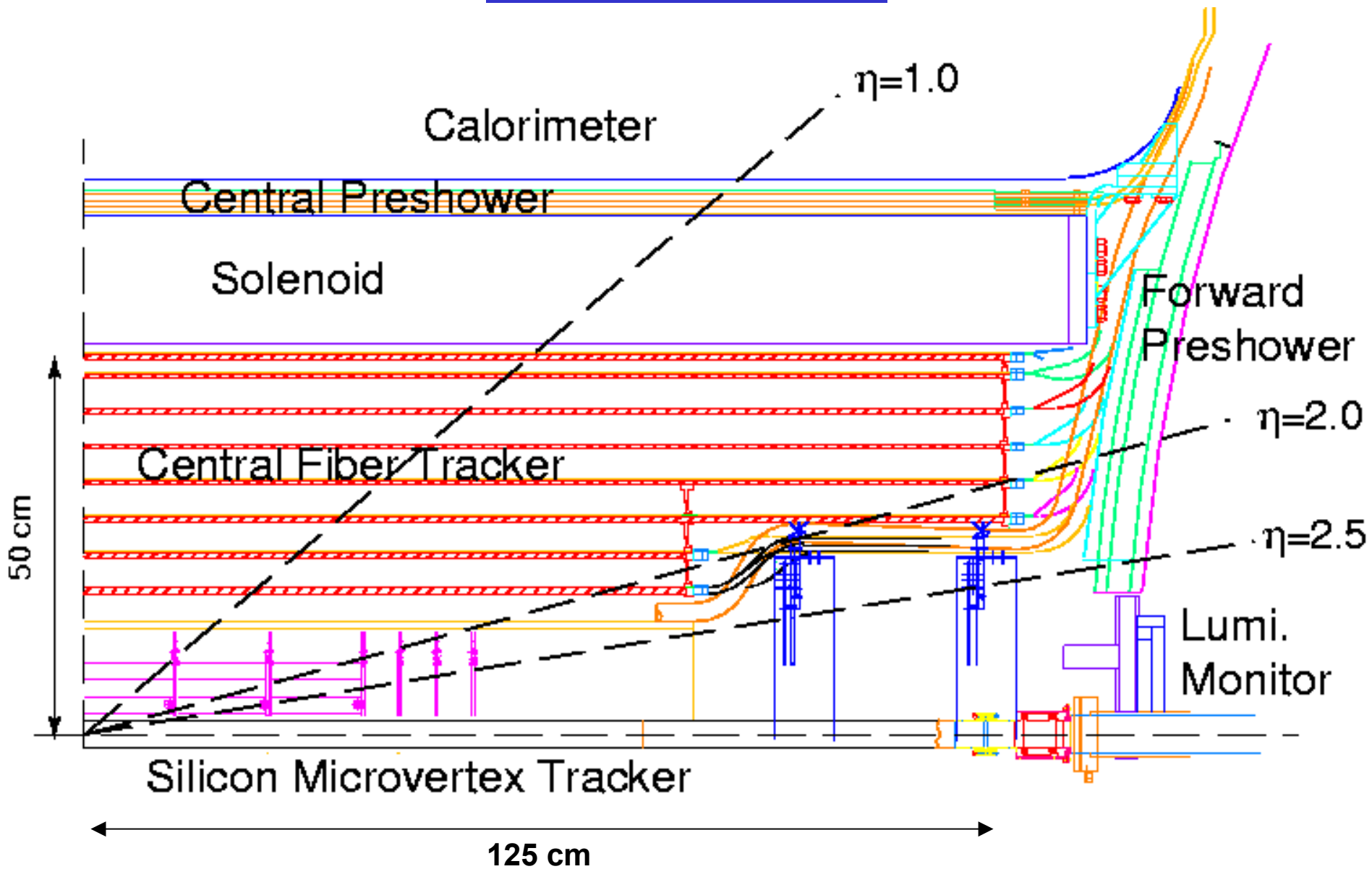
2D Impact Parameter Resolution



The Run II DØ Detector

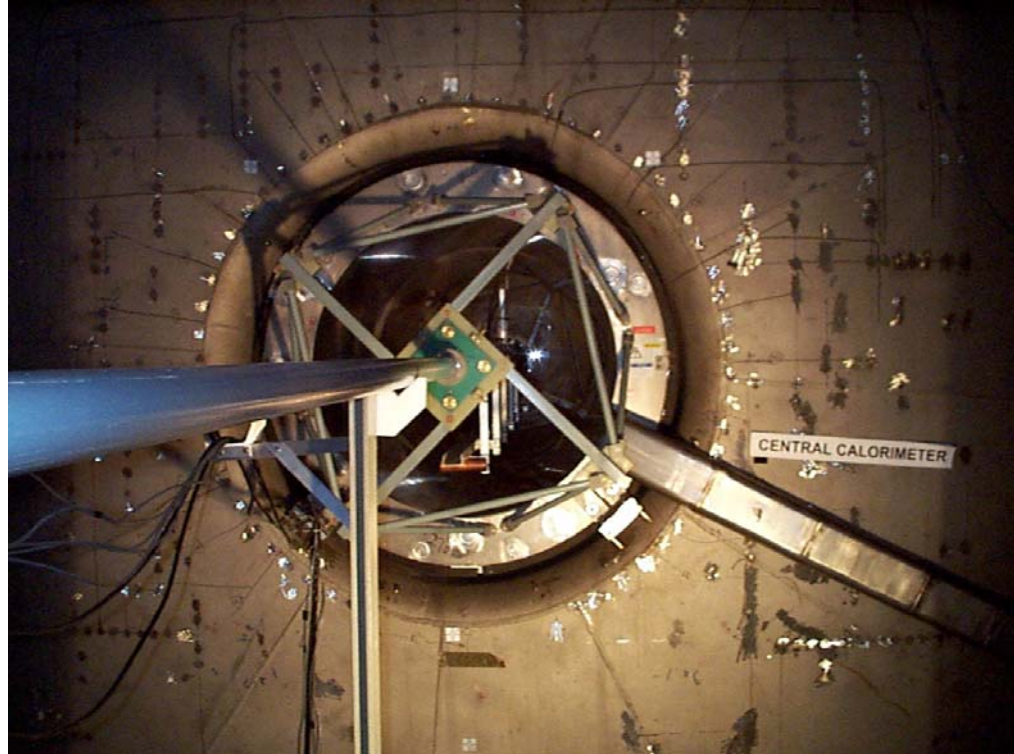


DØ Tracker

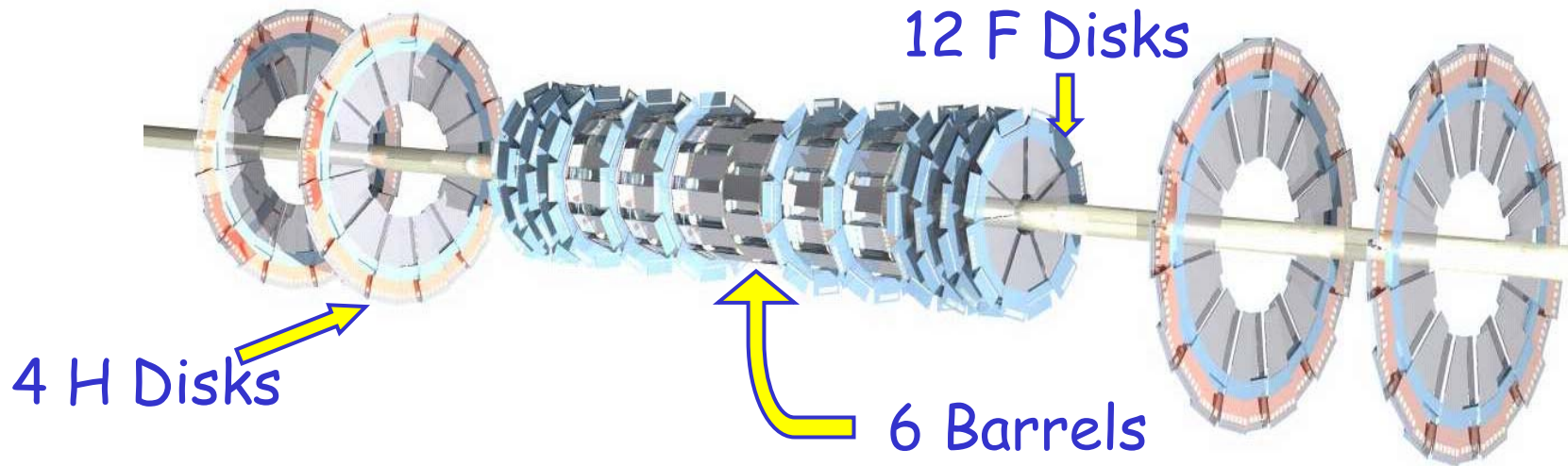


Solenoid

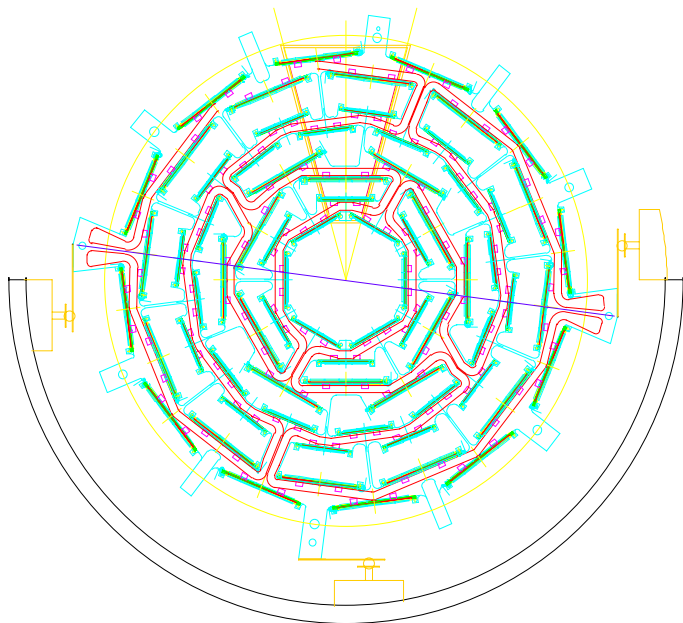
- 2.7 m long 2 Tesla field
- 5 MJ stored energy
- Two layer superconducting coil with mean radius of 60 cm
- $\sin\theta \int B_z dl$ is uniform to within 0.5%
 - achieved using two grades of conductors with higher densities near ends of coils
- Coil and cryostat ≈ 0.9 rad lengths
- Manufactured by Toshiba Corporation
- Delivered May 97



Silicon Microstrip Tracker (SMT)



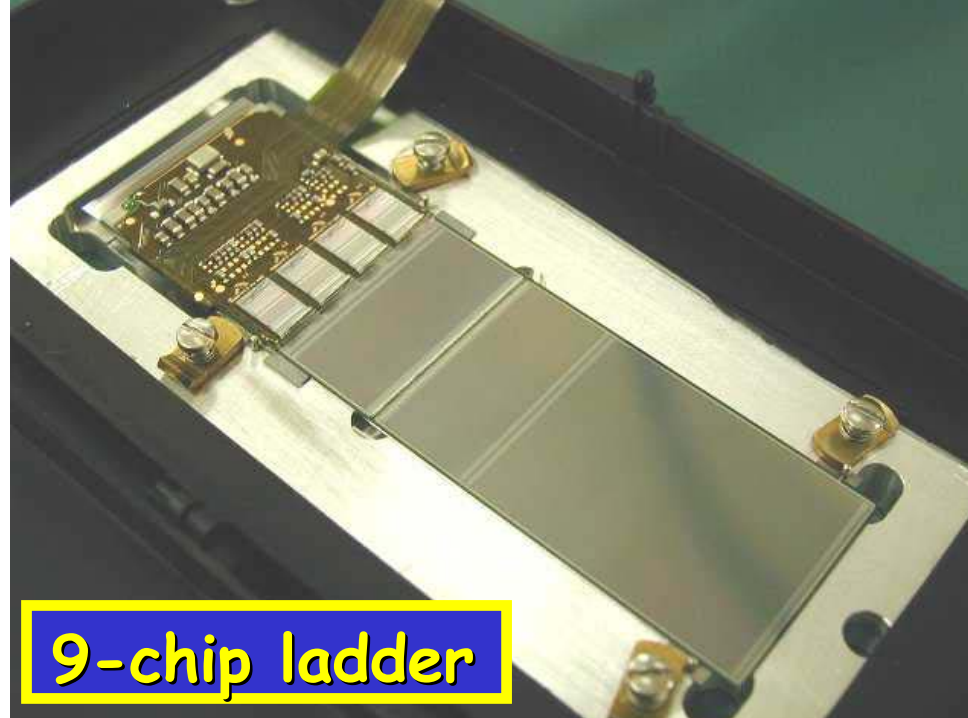
4-layer barrel cross-section



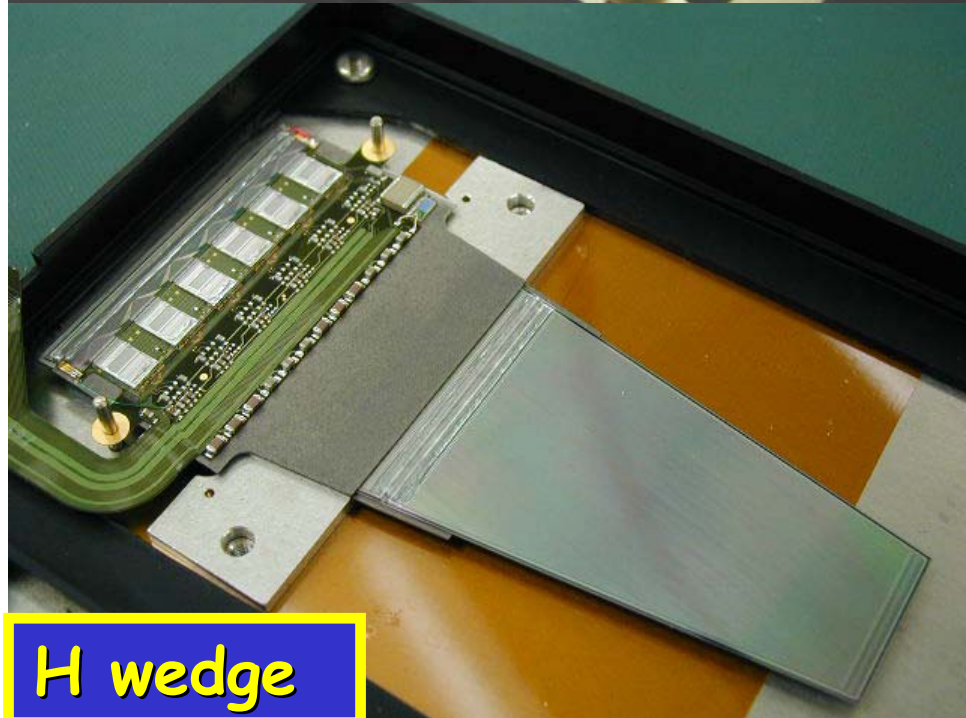
	Barrels	F-Disks	H-Disks
	sngr + dbl	double	single
Stereo	0, 2, 90	+/-15	+/-7.5
Channels	387072	258048	147456
Modules	432	144	96
Inner R	2.7 cm	2.6 cm	9.5 cm
Outer R	9.4 cm	10.5 cm	26 cm

SMT

- 793K channels
- 3 m² of silicon
- >2.3 million wirebonds
- Ladders
 - 3-chip: 72 single-sided, axial ladders in the two outer barrels
 - 6-chip: 144 double-sided, axial/90° ladders in the four inner barrels
 - 9-chip: 216 double-sided, axial/2° ladders in all barrels
 - Mechanical accuracy of 2 to 5 μm
- Wedges
 - F Disks: 144 double-sided, ±15°, 6+8 chip wedges
 - H Disks: 96×2 back-to-back single-sided, ±7.5°, 6 chip wedges
 - Mechanical accuracy of 5 to 10 μm
- CMM aligned ladders and wedges to better than 20 μm

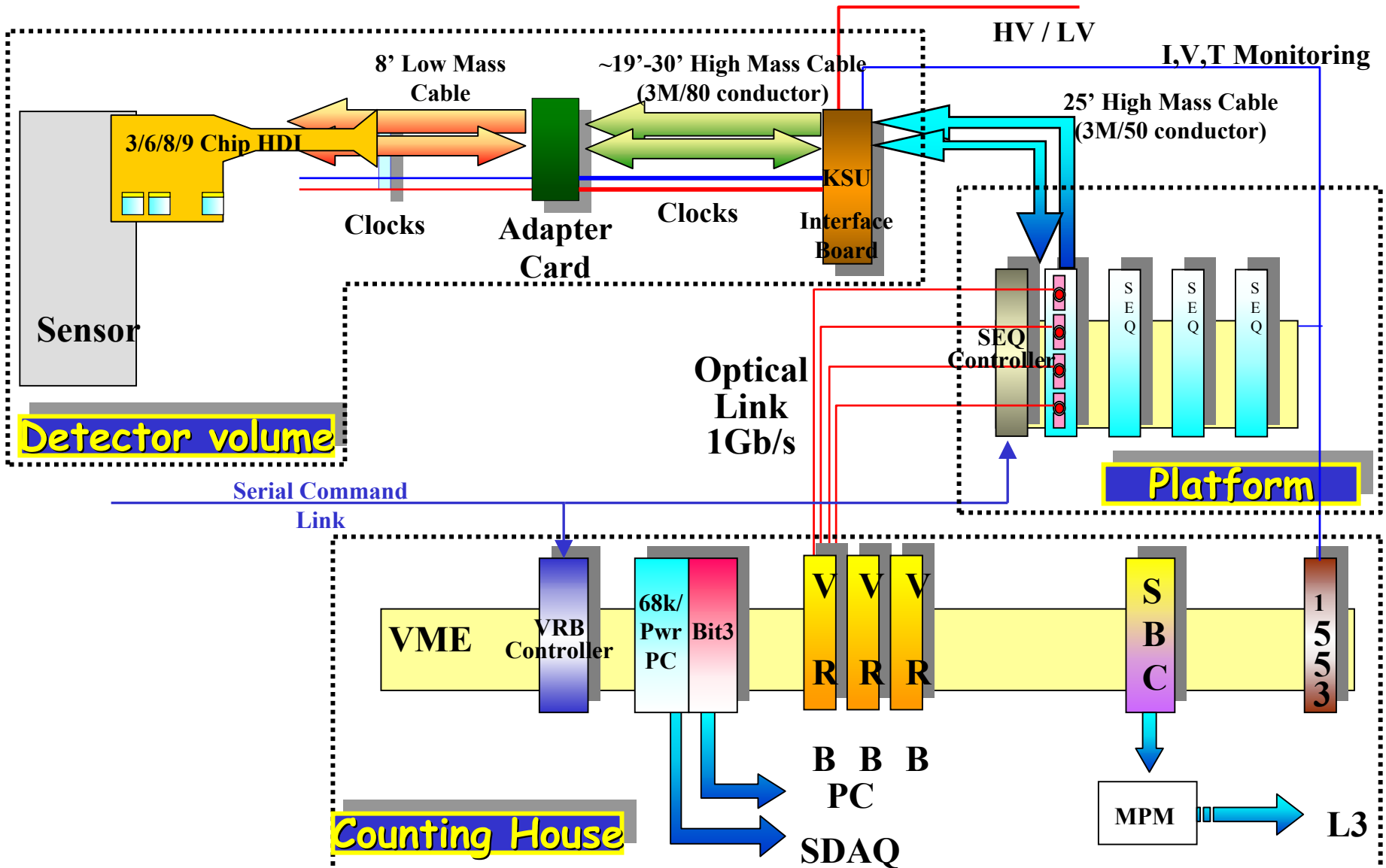


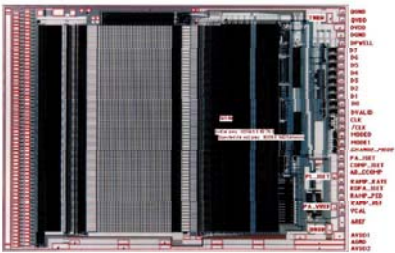
9-chip ladder



H wedge

SMT Readout: Data Flow





SMT Readout Electronics

● SVX ITe Chip

- Design by LBL and Fermilab
- 1.2 μm radiation hard tech.
- 128 channels per chip
- 32 cell pipeline depth
- 8 bit ADC with sparsification
- 106 MHz digitization
53 MHz readout

● Interface Boards

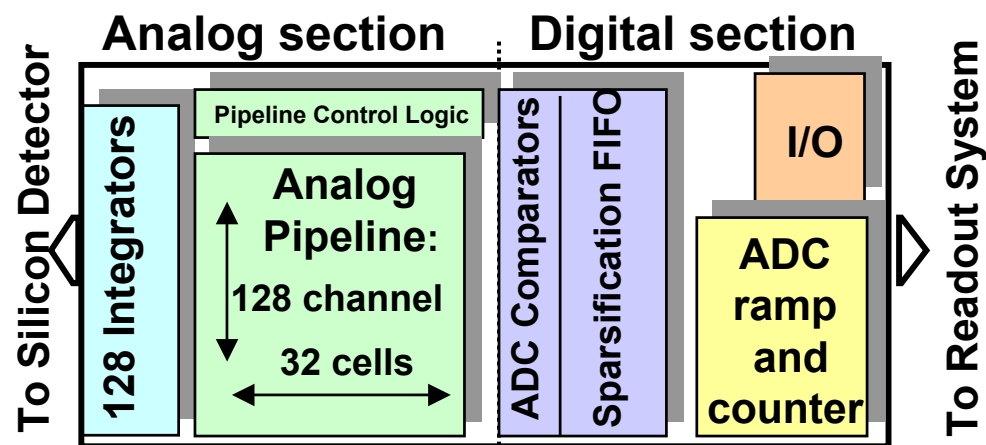
- Refresh signals and adjust timing
- Power management and monitoring

● SEQencers

- Management of SVX
- Fiber optic output

● VME Readout Buffer

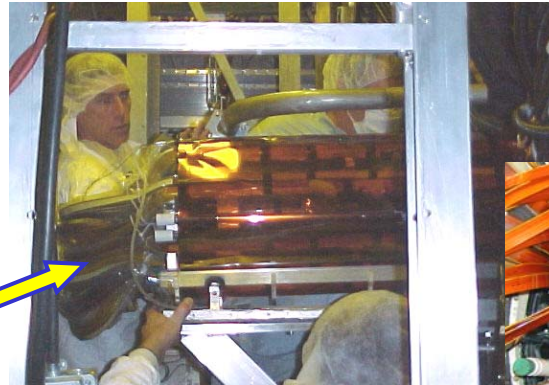
- Data buffer pending L2 trigger decision
- ~ 50 Mb/s/channel
- 10 kHz L1 accept
- 1 kHz L2 accept rate



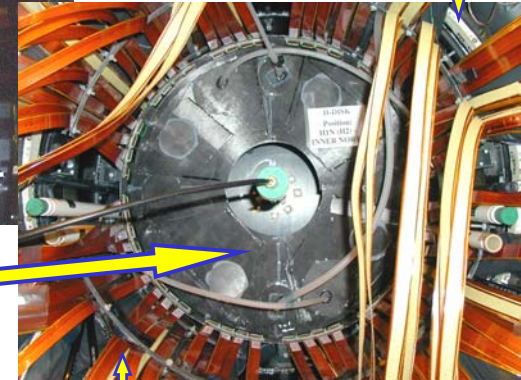
SMT Installation



- Cylinder installation completed Dec 2000
 - A $\frac{1}{2}$ cylinder of 3 barrels and 6 F disks was inserted into each end of the CFT bore
- H Disk installation completed Feb 2001
- The cabling (~15,000 connections) and electronics installation was completed in May 2001



Fiber Tracker



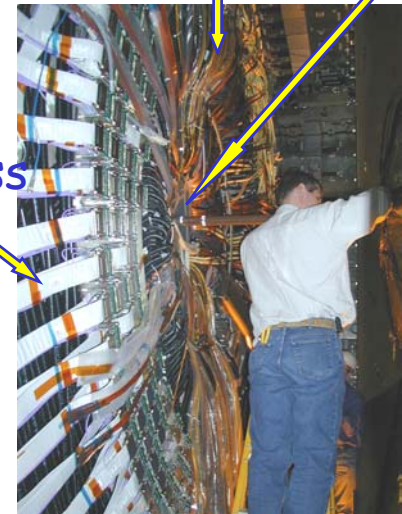
Calorimeter



Low Mass Cables

SMT

High Mass Cables



Interface Boards

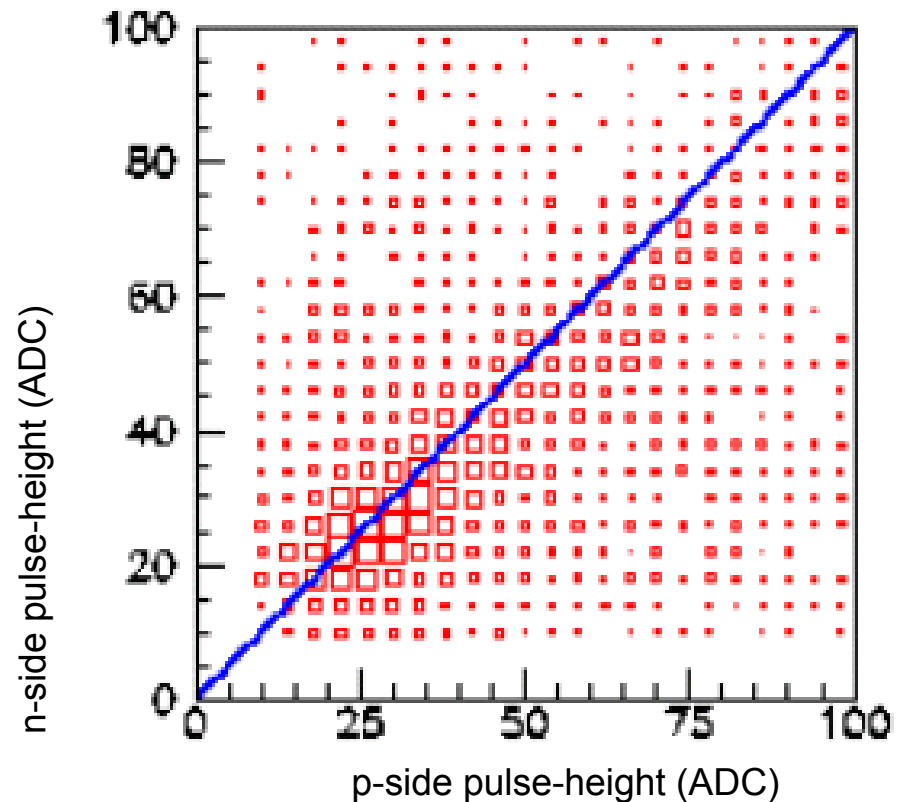
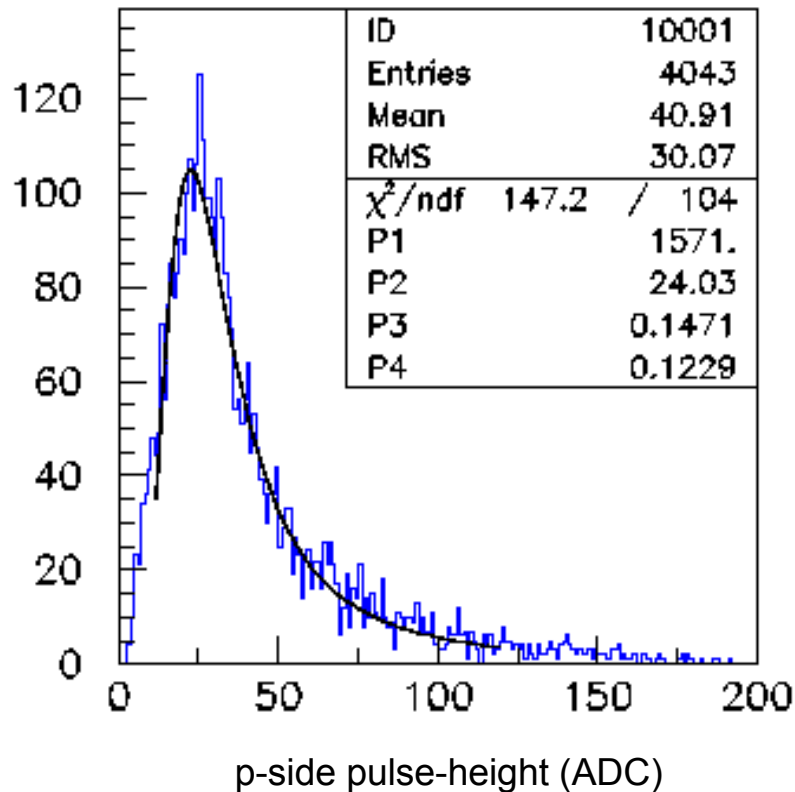
SMT Charge Collection

Cluster charge

(corrected for track angle):

- 1 mip \Rightarrow $\sim 4fC \Rightarrow$ 25 ADC counts
- Noise < 2 ADC counts

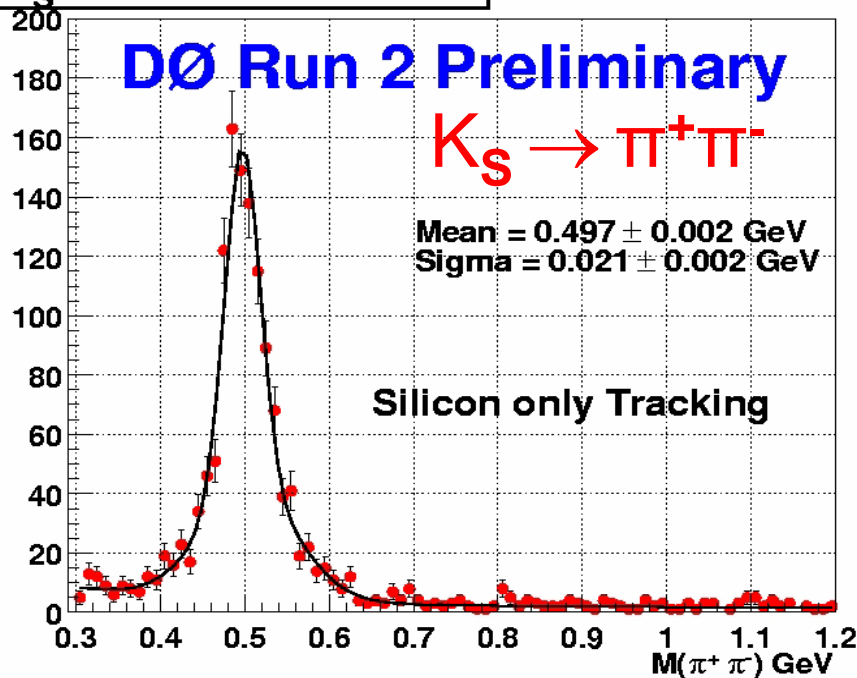
Charge correlation between p- and n-side of a detector



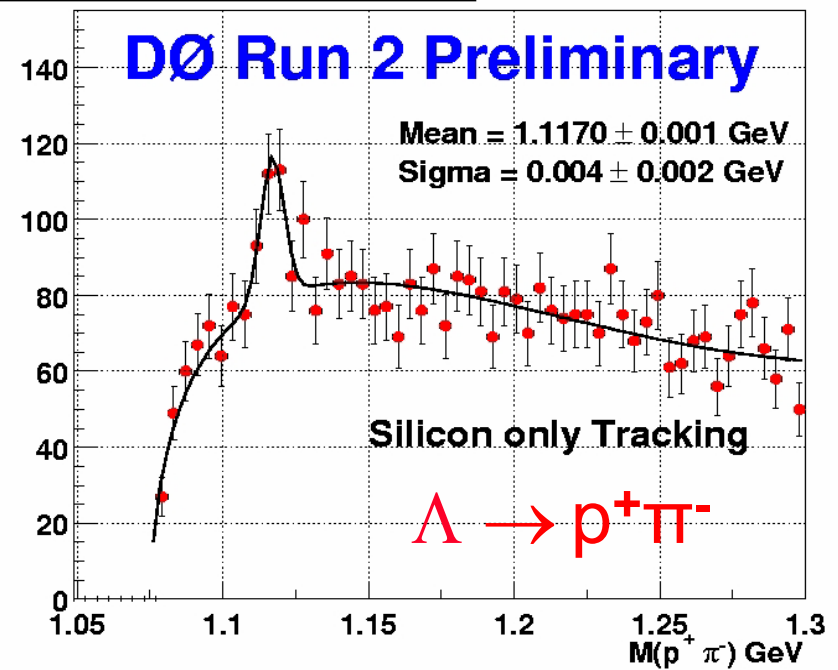
SMT Results

- $\approx 95\%$ of SMT channels available for readout
- Hit efficiencies for good single silicon detectors $> 97\%$
- Explicit V^0 reconstruction using SMT only tracks

K_S^0 Invariant Mass



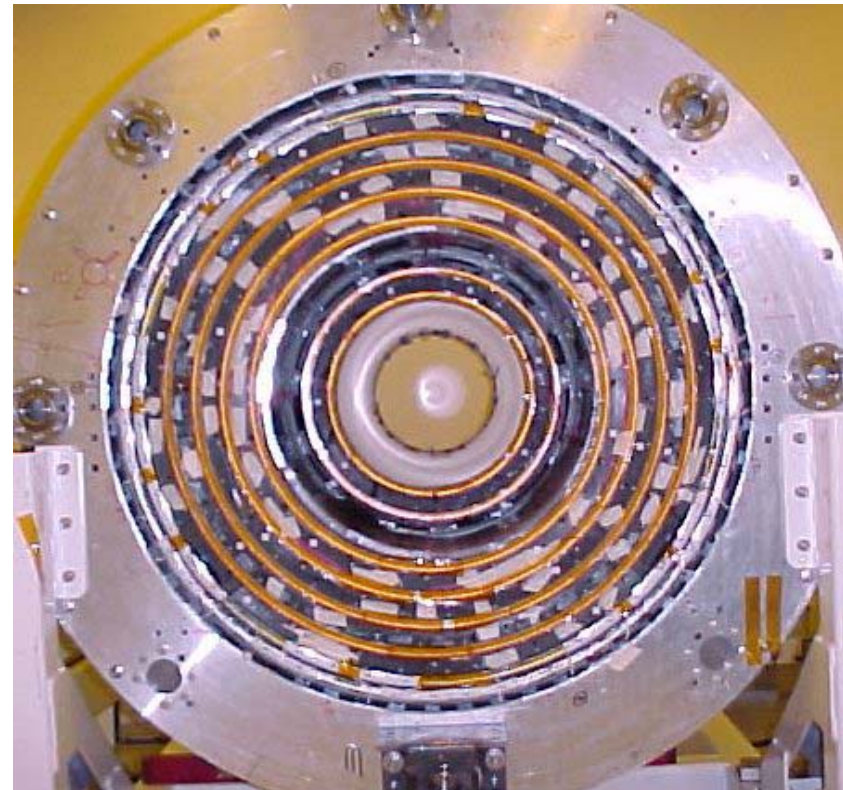
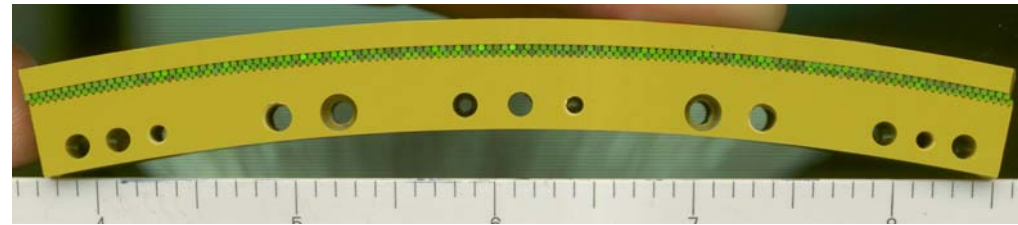
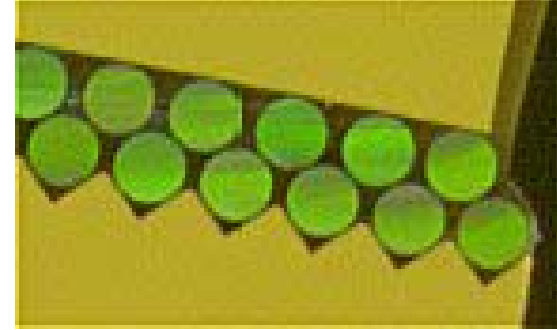
Λ Invariant Mass



- Work in progress on geometry and alignment, charge sharing and clustering to improve resolutions, and performance

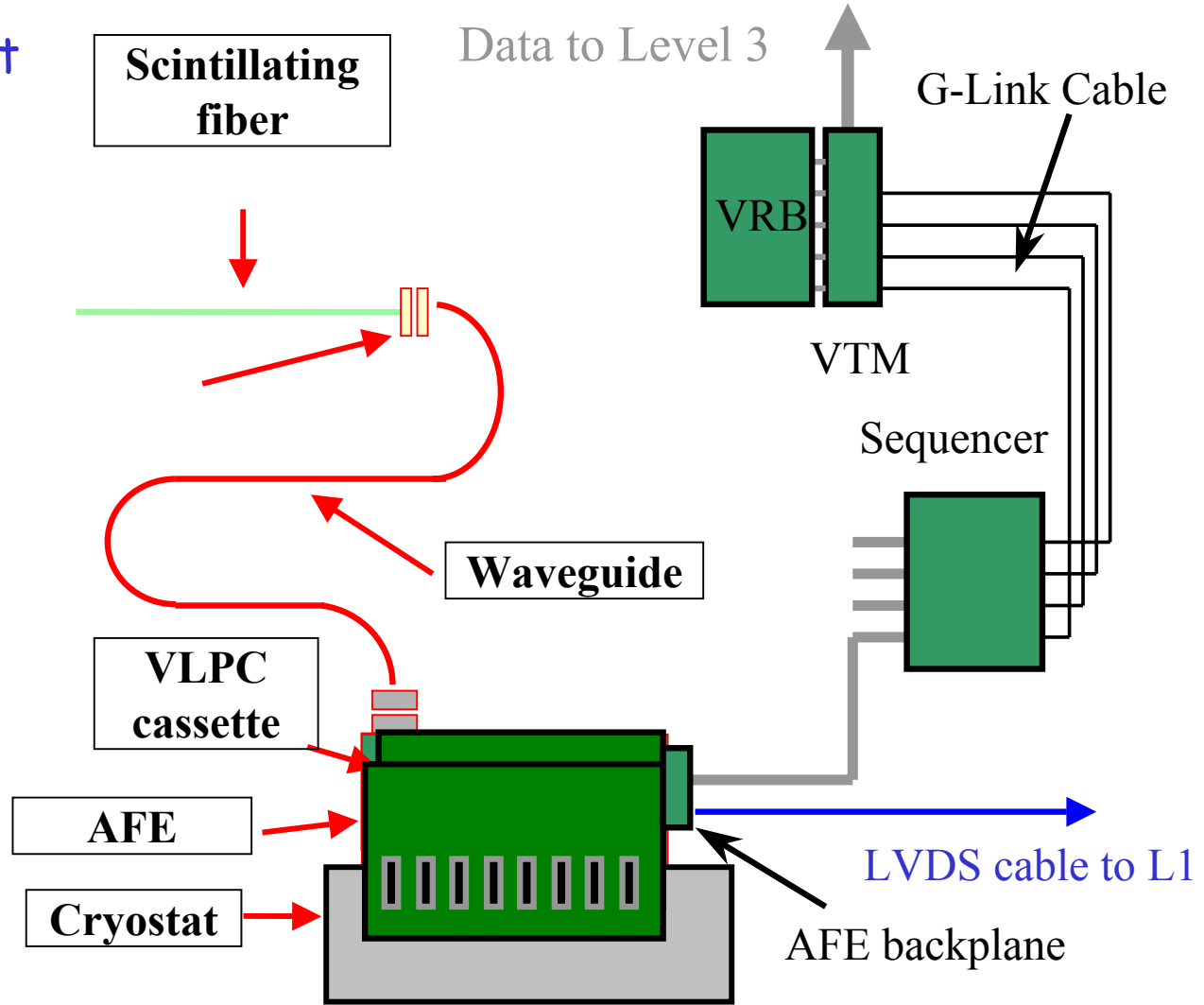
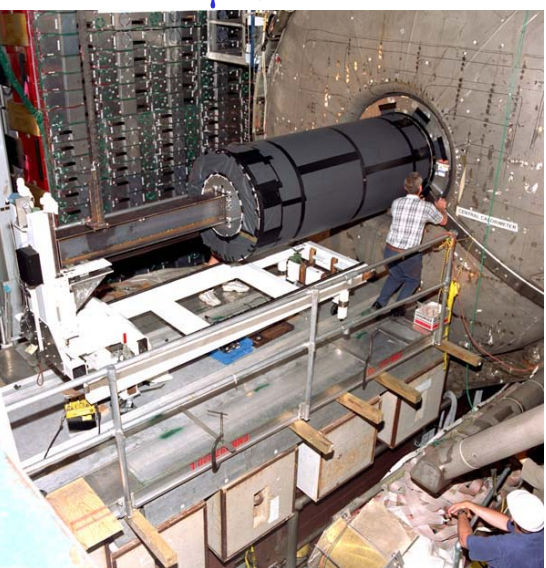
Central Fiber Tracker (CFT)

- 835 μm diameter multi-clad scintillating fibers arranged into precisely positioned ribbons of interlocked fiber doublets
- 256 fibers per ribbon
- Pairs of ribbons mounted on outside surface of eight carbon fiber support cylinders
- Inner ribbons on each cylinder have fibers oriented along the cylinder axis (axial view)
- Outer ribbons on each cylinder have fibers oriented at $\pm 3^\circ$ angle (stereo view)
- Scintillating fibers on outer six cylinders are 2.5 m long



CFT Readout

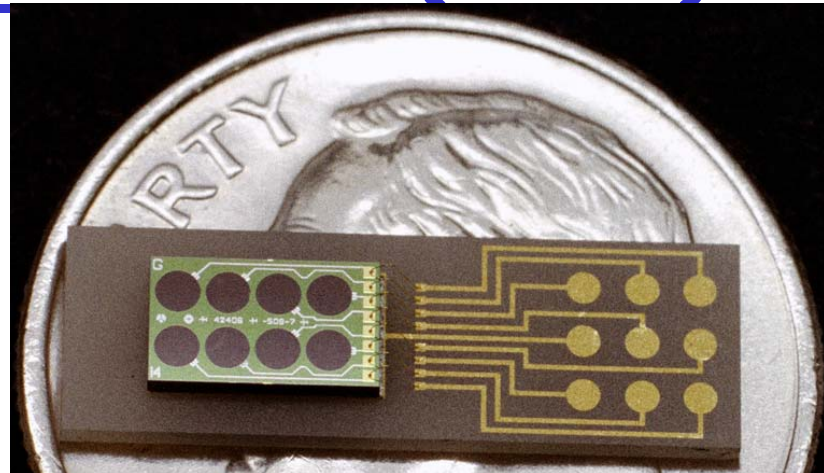
- Total of 76800 scintillating fibers
- Bundles of 8.2 to 11.4 m long clear fibers (waveguides) pipe light to individual light sensitive detectors (Visible Light Photon Counter pixels)
- ≈ 10 photons to VLPCs
- Position resolution of fiber doublet is $\approx 100\mu\text{m}$



Visible Light Photon Counters (VLPC)

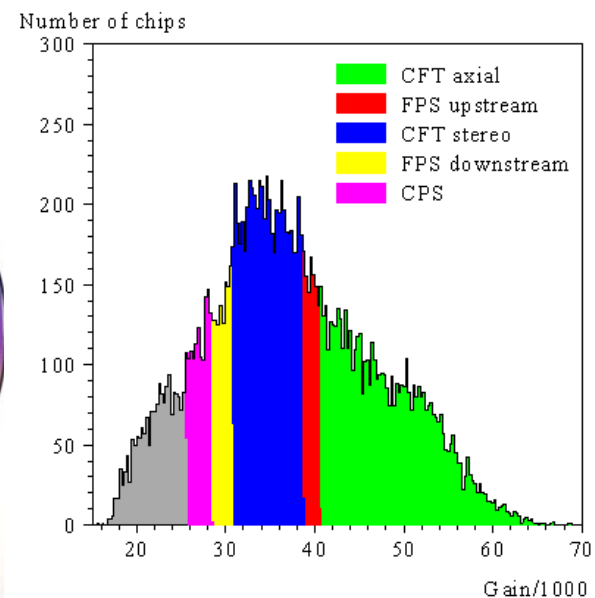
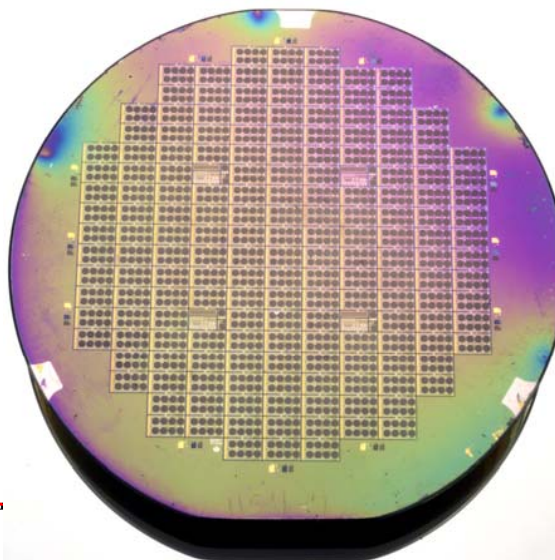
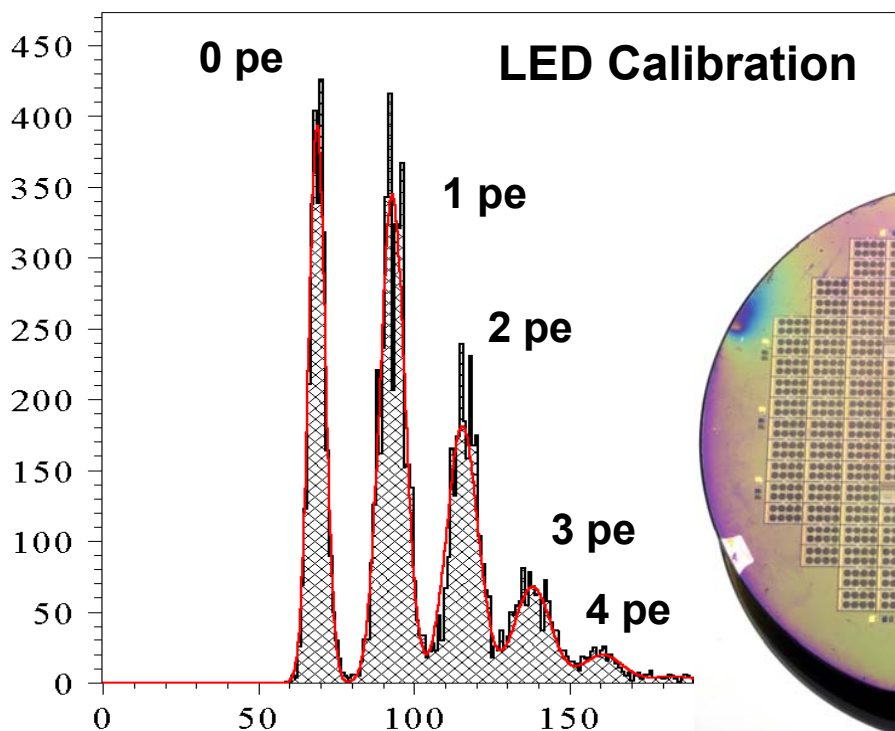
solid state photo-detectors

- 1 mm diameter pixels arranged in 2x4 array
- function at high rates
- quantum efficiency $\approx 80\%$
- low gain dispersion
- operated at $9\text{K} \pm 0.05\text{K}$



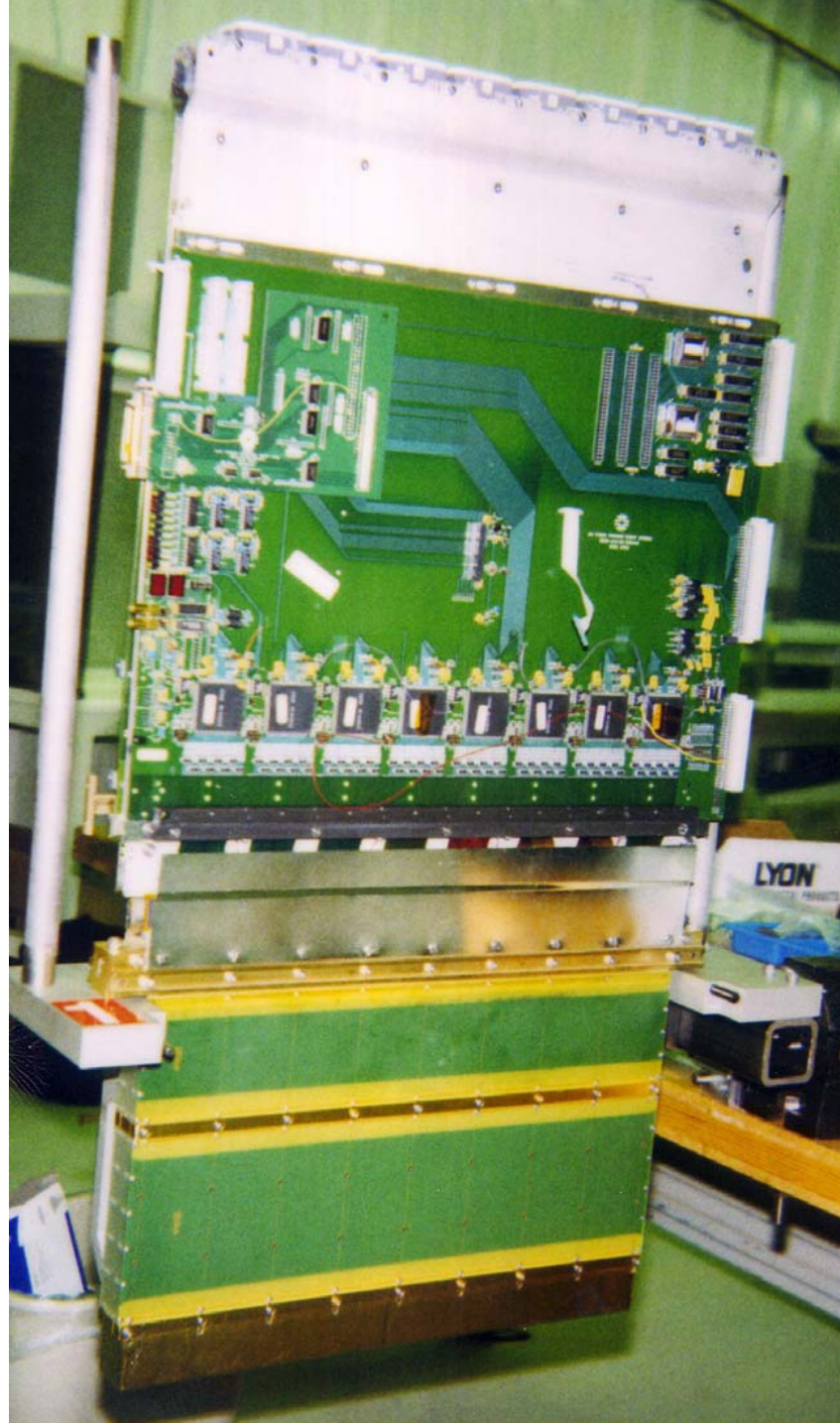
VLPC fabricated in wafers of 176 chips

- gain, optimal bias voltage, relative QE, and rate effects vary among and across wafers



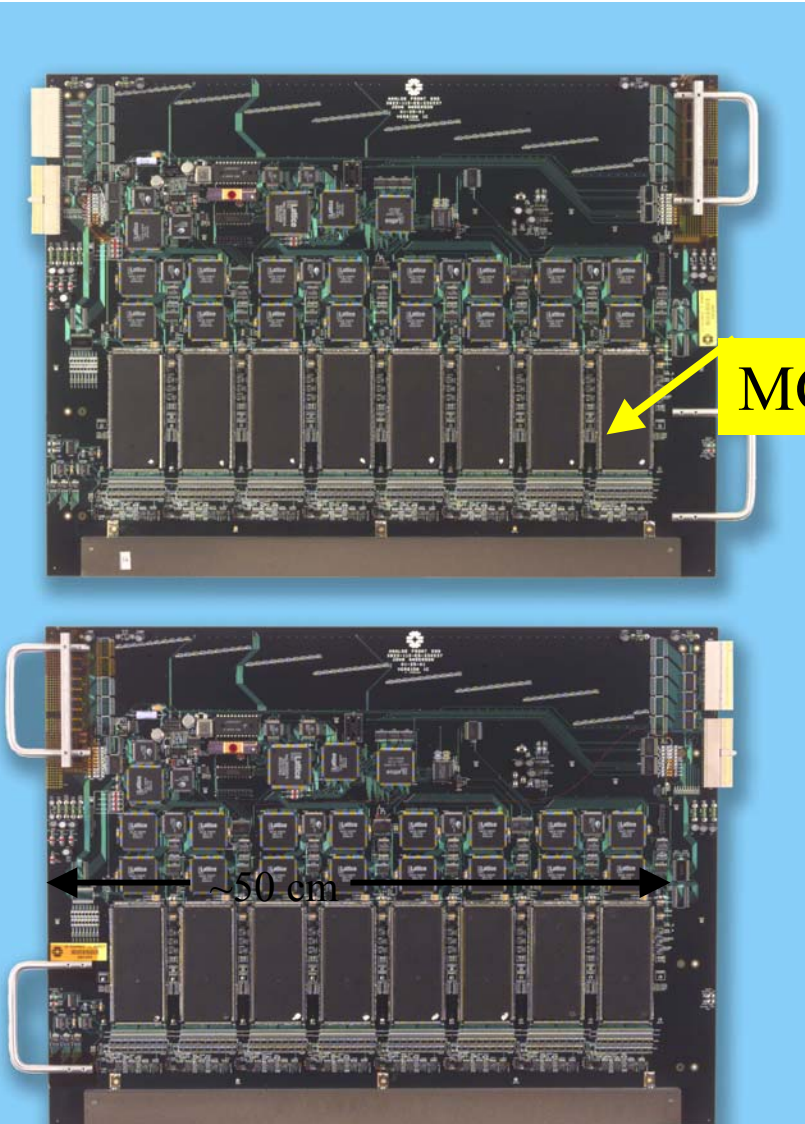
VLPC Cassette

- VLPC performance is sensitive to the operating temperature, bias voltage, and the background rate
- Optimize VLPC performance by grouping chips which exhibit similar characteristics
- Cassettes provide mechanical support, optical alignment, and appropriate operating services for proper operation and readout of the VLPCs
- 1024 channels of VLPC readout per cassette organized into eight independent modules of 128 channels
- Lower portion immersed in gas Helium
- Upper portion supports printed circuit board for trigger and readout



Analog Front End Boards (AFE)

- 512 channels per AFE board
 - ~8 photoelectrons per MIP → ~50 fC signal
 - SVX IIE chip for pulse height information
 - discriminated output for trigger
 - VLPC temperature control and monitoring
 - 9K with $\pm 0.050\text{K}$ precision
 - VLPC bias voltage control and monitoring
 - 6 to 8 V with $\pm 0.050\text{V}$ precision
- AFE boards controlled by SEQuencers and data is readout to VRBs (similar to SMT readout)
- CFT axial fully instrumented by Jan 2002
- CFT stereo fully instrumented by April 2002

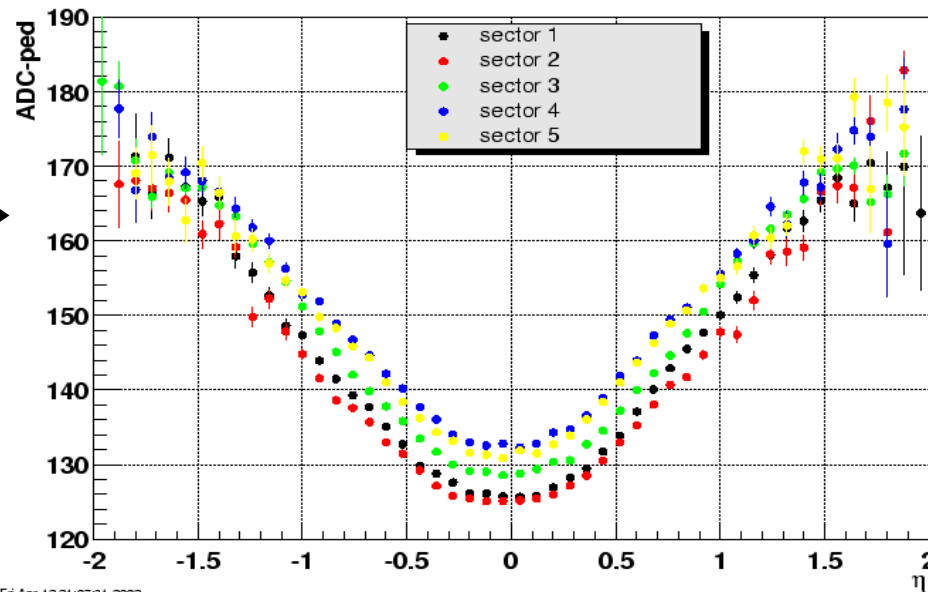


CFT Performance

Light yield depends upon path length through scintillator

Using good 15 hit CFT tracks, the probability of a cluster within a 3 or 5 σ search window of track in excluded layer is better than 96.5% or 98% respectively

Run 149204: adc vs η (axial sectors)

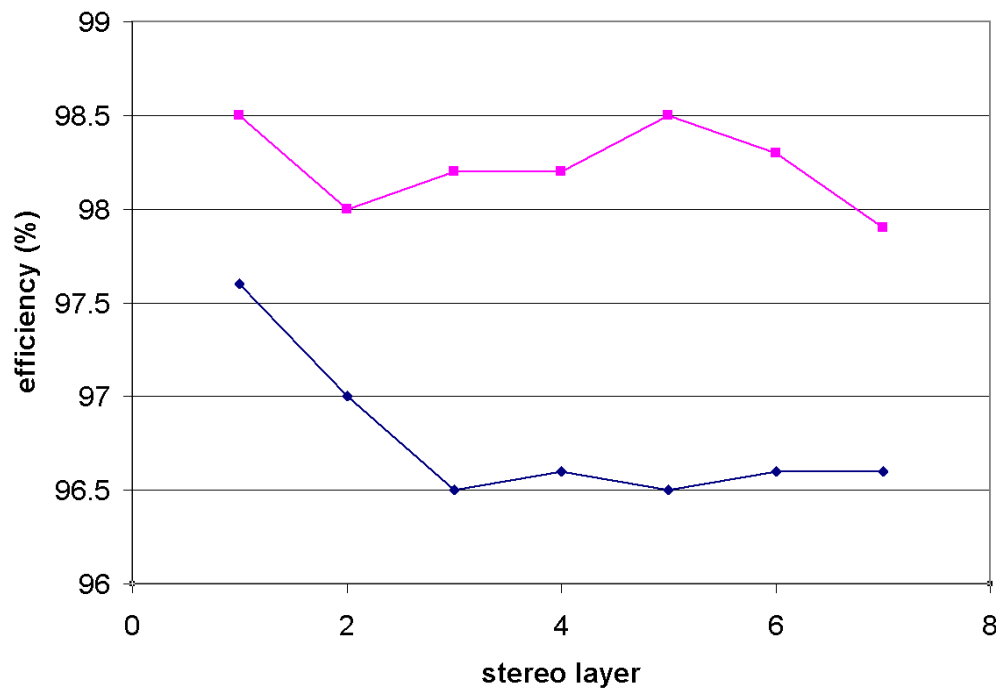


Fri Apr 12 21:07:31 2002

Mean light yield as a function of pseudorapidity

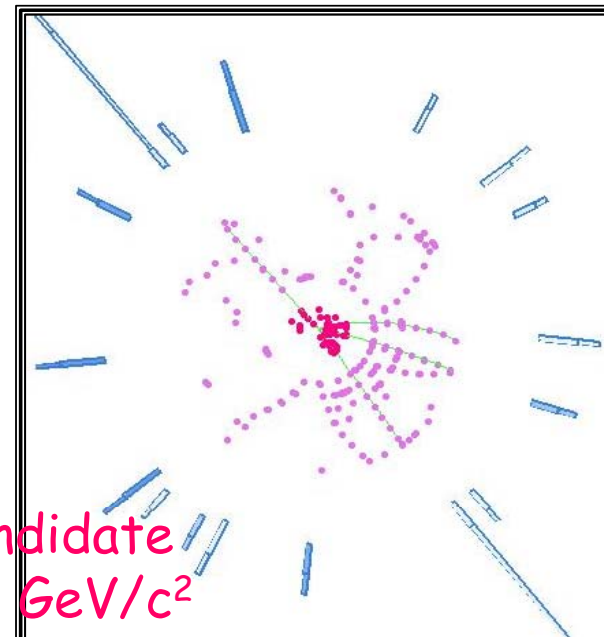
Single track hit efficiencies

Chart Area



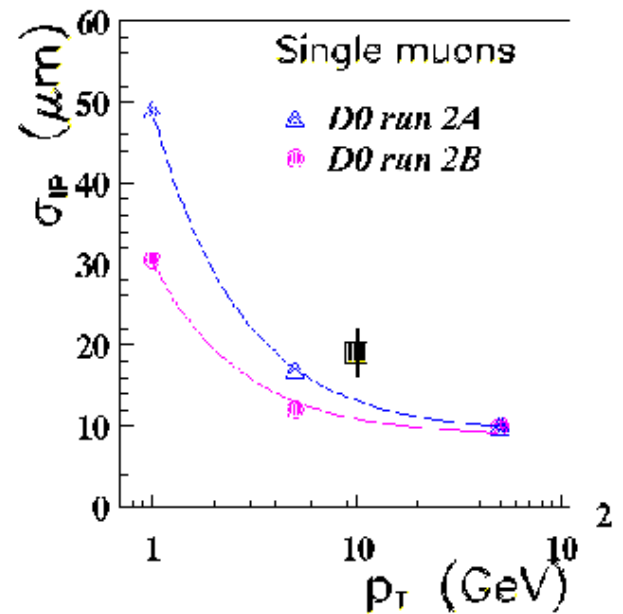
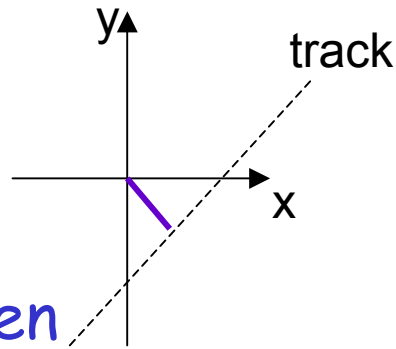
—◆— 3 sigma
—■— 5 sigma

Z \rightarrow ee candidate
Mass 89.9 GeV/c²

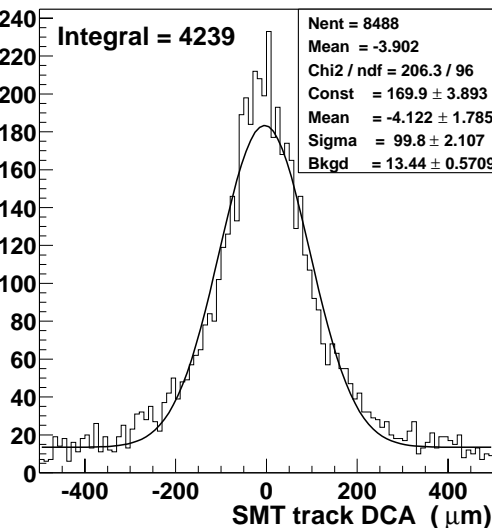


Tracking Performance

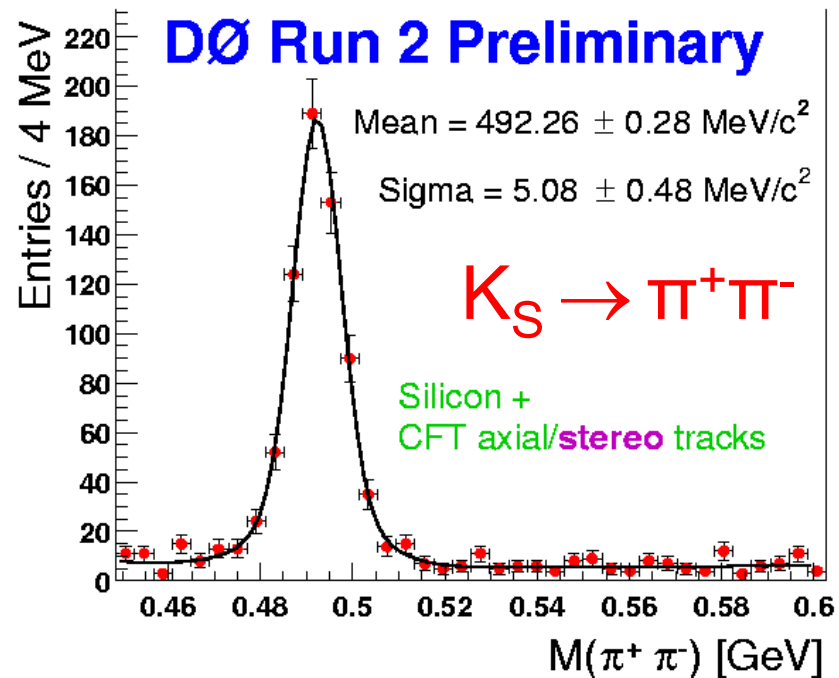
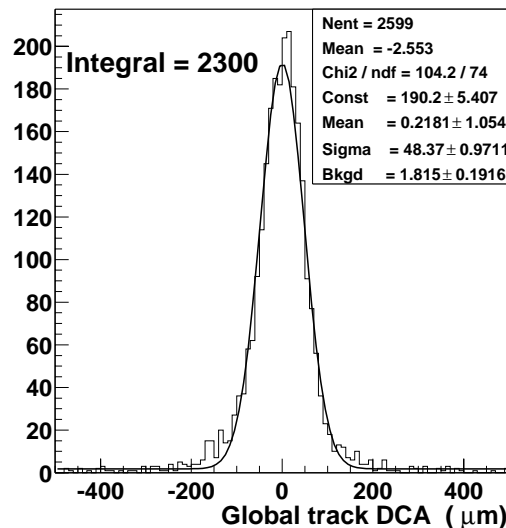
p_T dependent impact parameter resolution at vertex is $\approx 100 \mu\text{m}$ using SMT only tracks and improves to $\approx 48 \mu\text{m}$ when CFT data is combined with SMT data--and is expected to improve further as studies progress



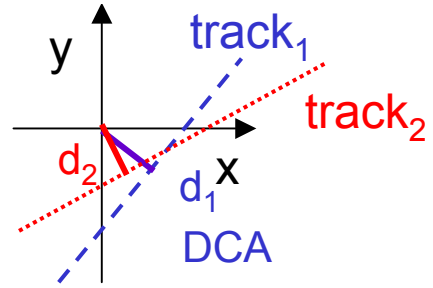
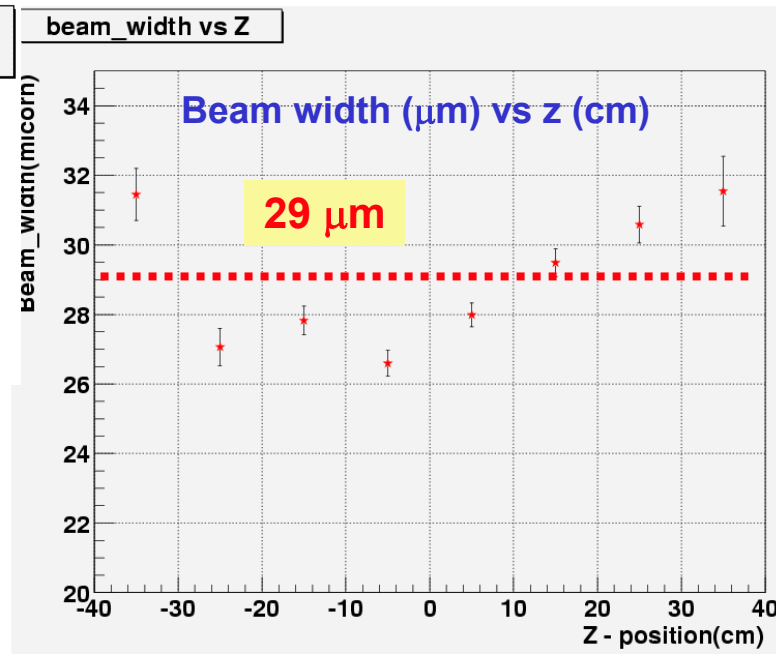
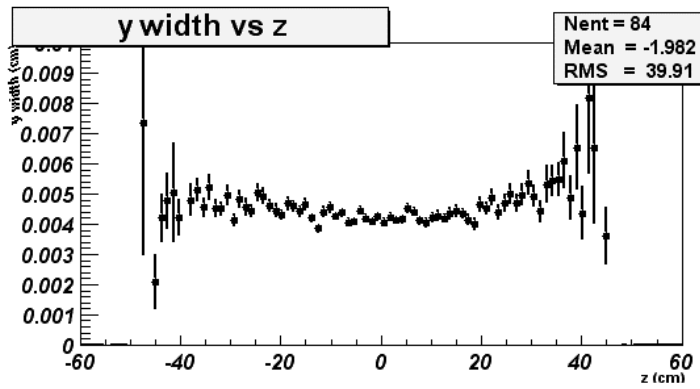
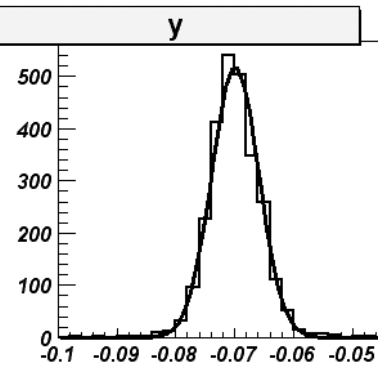
Run 143482 bgv



Run 143482 bgv

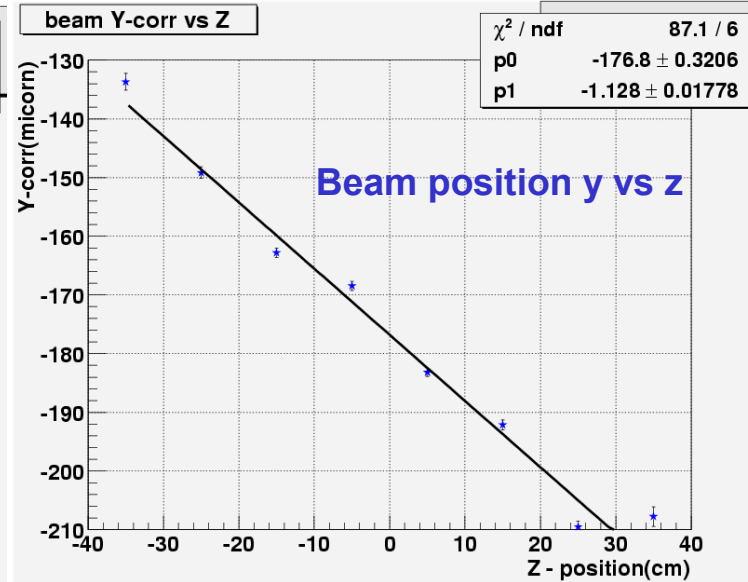
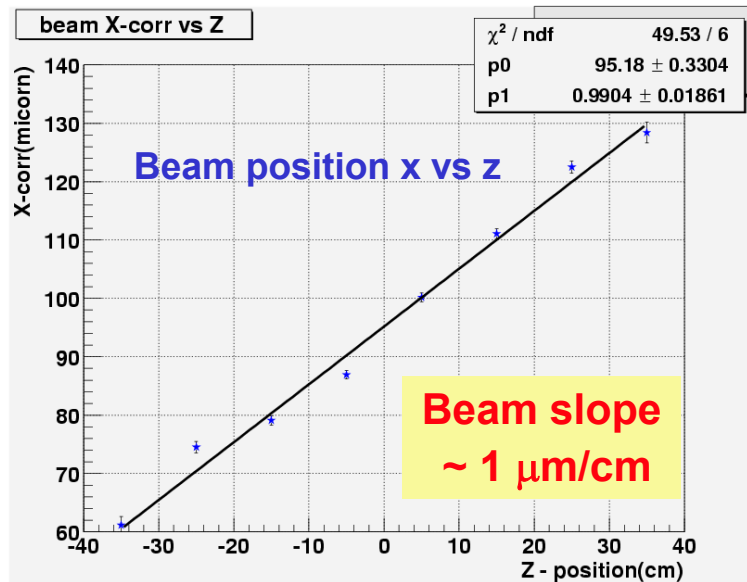


Beam Position and Alignment

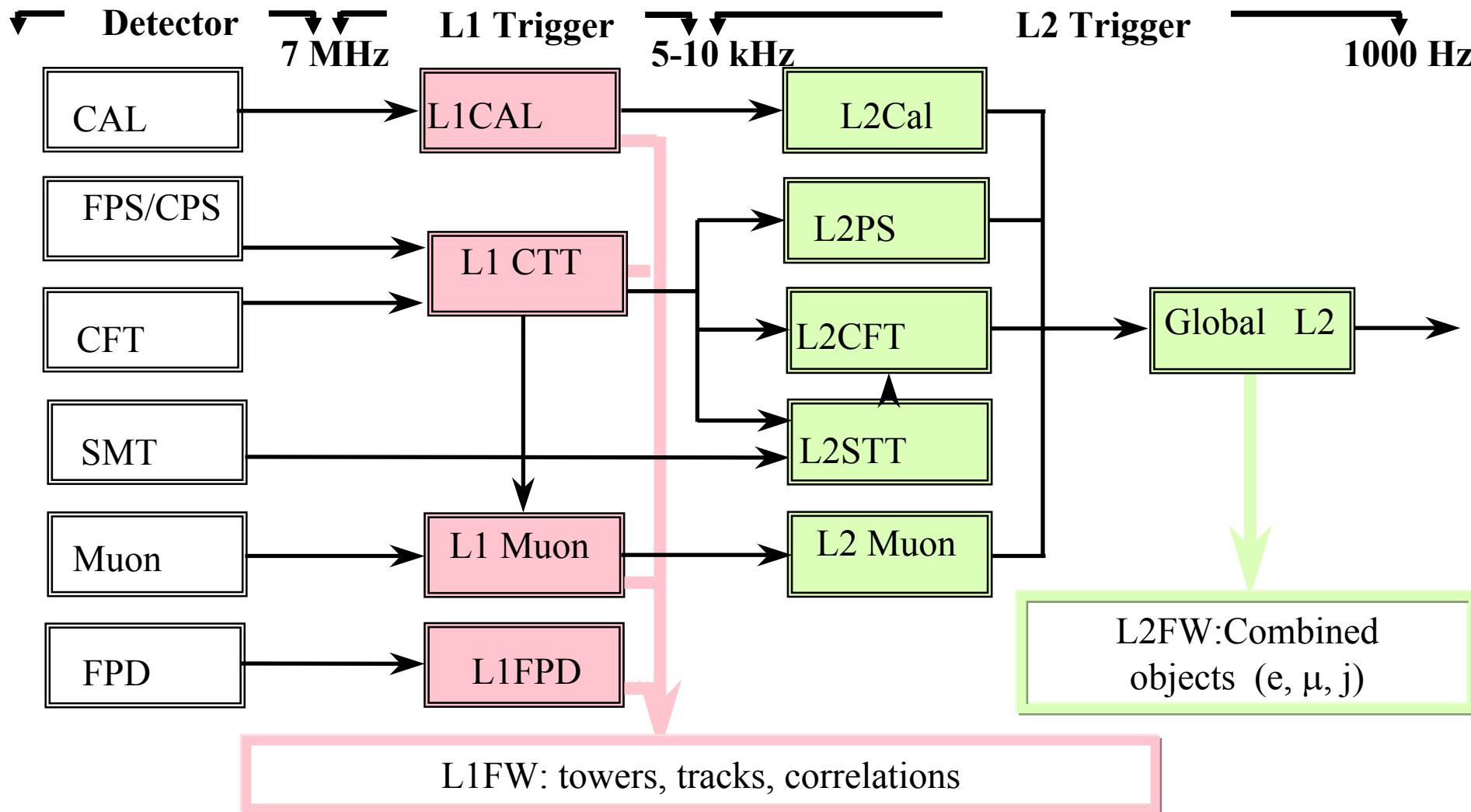


Impact parameter resolution (DCA) for global tracks (CFT axial + stereo + SMT)

Compare $d_1 d_2$ vs $\cos \phi_{12}$ to extract beam width

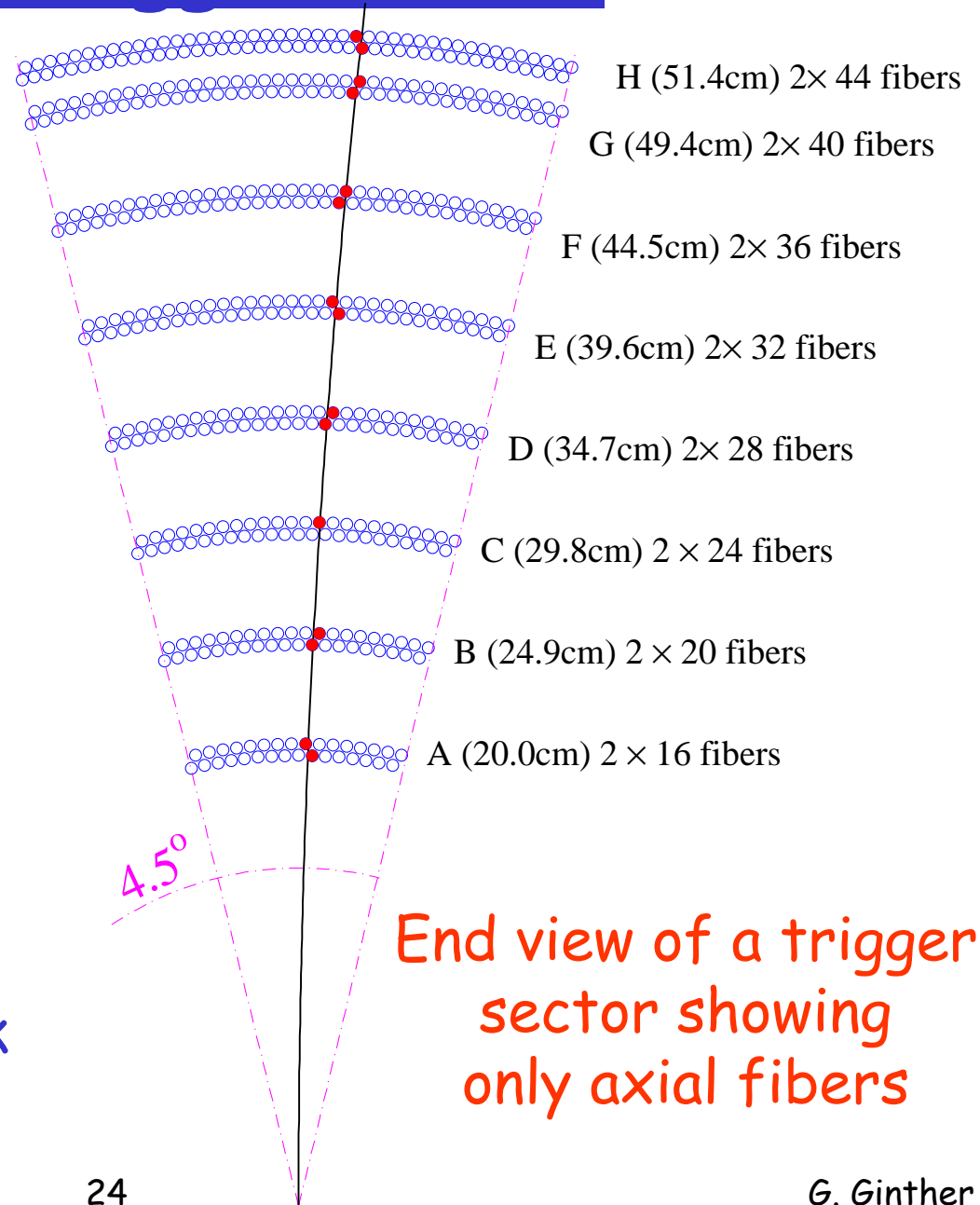


DØ Trigger System



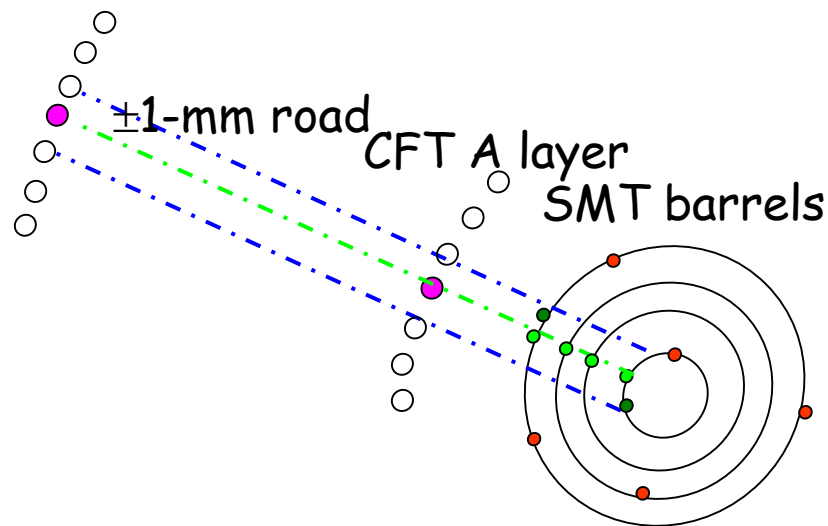
Central Track Trigger (CTT)

- Counts track candidates identified in axial view of CFT by looking for hits in all 8 axial layers within predetermined roads above four Pt thresholds (1.5, 3, 5, and 10 GeV/c)
- Combines tracking and preshower information to identify electron and photon candidates
- Generates track lists allowing other trigger systems to perform track matching

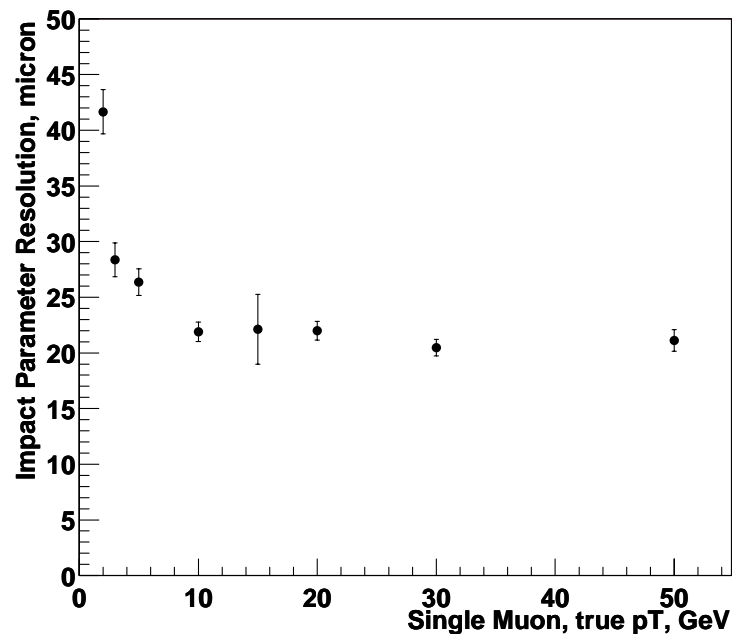


Silicon Track Trigger

- Combines inputs from CFT and SMT at Level 2 to select events
- Axial clusters matched to ± 1 mm wide roads around each CFT axial track via precomputed look up table

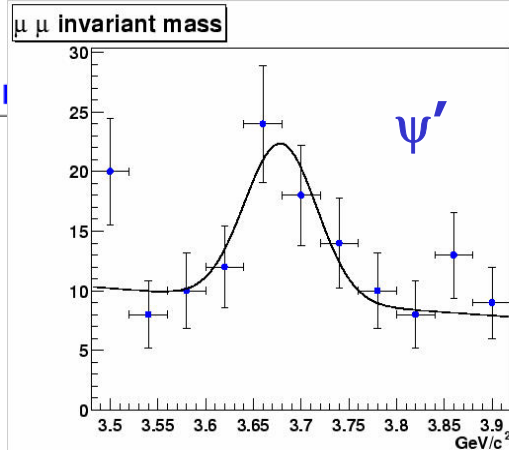
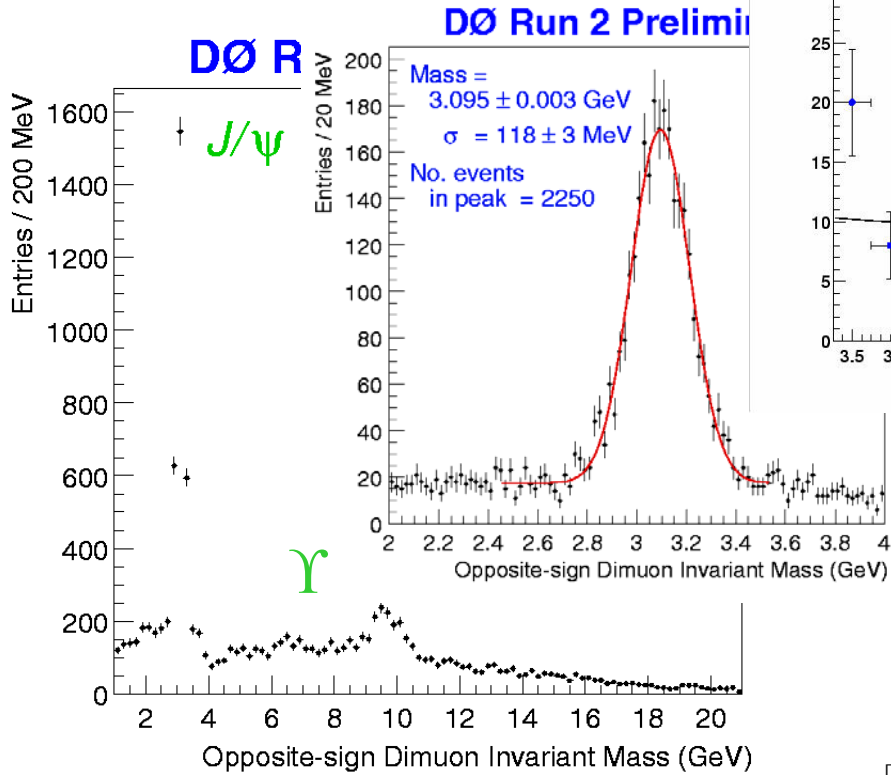


Impact Parameter Resolution vs. pT

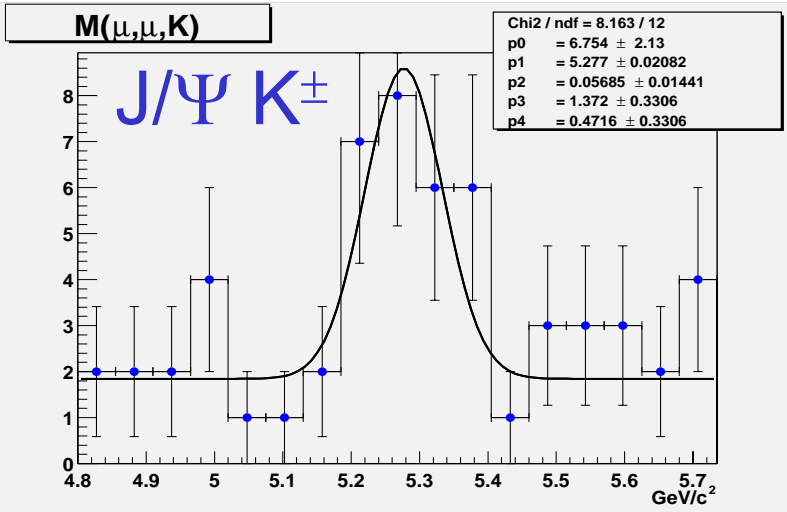
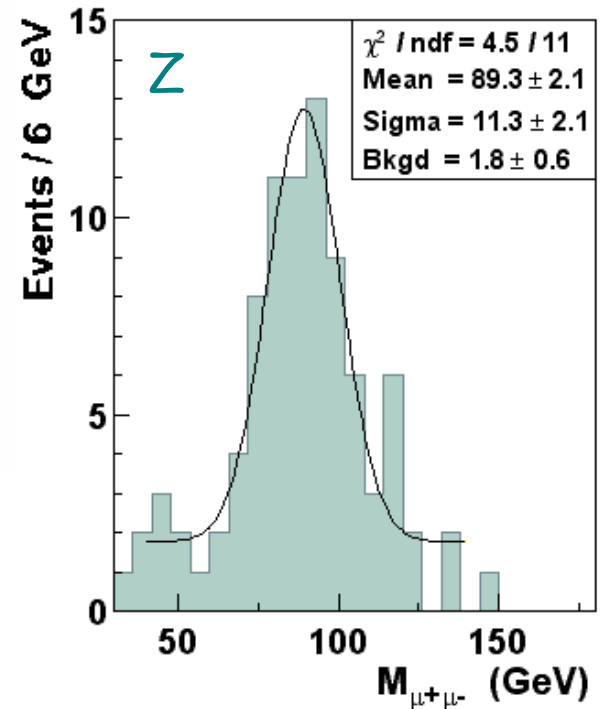


- Track fitting in Digital Signal Processors
- Prototypes of all boards in hand
- Hardware design complete and production in progress
- Firmware and integration tests ongoing

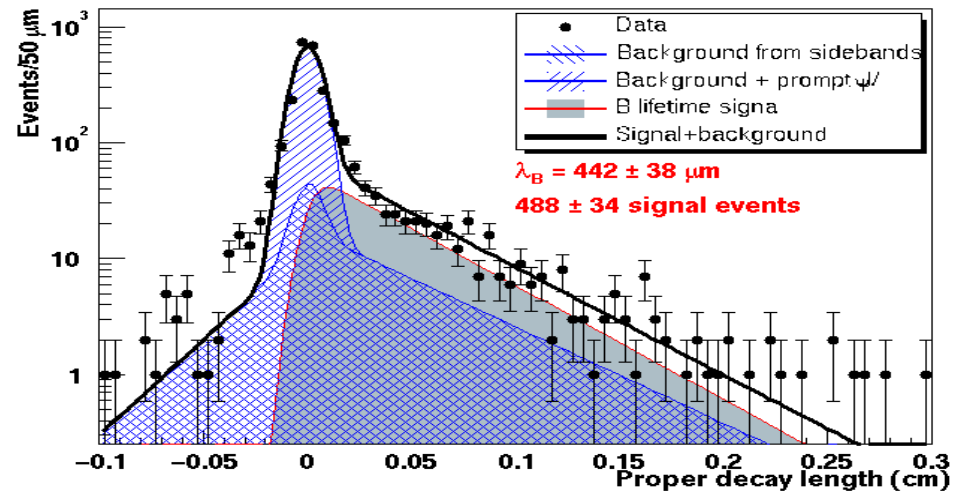
Physics Signals



**μ⁺μ⁻
mass**



Average B lifetime Evidence for B decays



DO

The work of many people including some shown here ⇒

Thanks to all of them!



The DØ Tracking System for Run II

● The Silicon Microstrip and Central Fiber Tracking systems are key components of the DØ Upgrade

- Tracking detectors designed to have good impact parameter resolution over wide range of η
- Readout system is generally stable and well behaved
- Detectors are performing well
- $\approx 95\%$ of the SMT channels are available for readout
- $> 98\%$ of the CFT channels are currently readout
- Optimization and tracking refinements continue
- CFT based triggering is currently being commissioned
- Silicon Track Trigger hardware and firmware developing
- Accumulation of data is in progress
- Physics results are coming in

Additional Related Information

- Silicon detector upgrades for TeV Run II B
Mark Kruse later in this session
- For an overview of the DØ detector for Run II
Levan Babukhadia in session RD-2 later today
- For a summary of recent results from DØ
Meena Narain in Monday morning plenary session

Multiple Interactions

